

June 2012

FDP039N08B_F102

N-Channel PowerTrench[®] MOSFET 80V, 171A, 3.9m Ω

Features

- $R_{DS(on)}$ = 3.16m Ω (Typ.) @ V_{GS} = 10V, I_D = 100A
- Low FOM R_{DS(on)}*Q_G
- Low reverse recovery charge, Q_{rr}
- · Soft reverse recovery body diode
- Enables highly efficiency in synchronous rectification
- · Fast Switching Speed
- 100% UIL Tested
- · RoHS Compliant

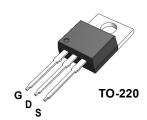


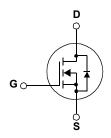
Description

This N-Channel MOSFET is produced using Fairchild Semiconductor's advanced PowerTrench process that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance.

Application

- · Synchronous Rectification for Server / Telecom PSU
- · Battery Charger and Battery Protection Circuit
- · DC motor drives and Uninterruptible Power Supplies
- · Micro Solar Inverter





MOSFET Maximum Ratings T_C = 25°C unless otherwise noted*

Symbol	Parameter			Ratings	Units
V _{DSS}	Drain to Source Voltage			80	V
V _{GSS}	Gate to Source Voltage			±20	V
		- Continuous (T _C = 25°C, S	ilicon Limited)	171*	
I_D	Drain Current	- Continuous (T _C = 25°C, P	ackage Limited)	120	Α
		- Continuous (T _C = 100°C,	Silicon Limited)	121	
I _{DM}	Drain Current	- Pulsed	(Note 1)	684	Α
E _{AS}	Single Pulsed Avalanche E	Single Pulsed Avalanche Energy (Note 2)			mJ
dv/dt	Peak Diode Recovery dv/d	t	(Note 3)	6.0	V/ns
D	Dower Dissination	$(T_C = 25^{\circ}C)$		214	W
P_{D}	Power Dissipation	- Derate above 25°C		1.43	W/°C
T _J , T _{STG}	Operating and Storage Temperature Range			-55 to +175	°C
T _L	Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds			300	°C

^{*} Package limitation current is 120A.

Thermal Characteristics

Symbol	Parameter	Ratings	Units
$R_{\theta JC}$	Thermal Resistance, Junction to Case	0.7	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient		30/00

Package Marking and Ordering Information

Device Marking	Device	Package	Description	Quantity
FDP039N08B	FDP039N08B_F102	TO-220	F102: Trimmed Leads	50

Electrical Characteristics T_C = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
Off Charac	cteristics					
BV _{DSS}	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	80	-	-	V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	I _D = 250μA, Referenced to 25°C	-	0.089	-	V/°C
Jaro Coto Voltago Drain Current		V _{DS} = 64V, V _{GS} = 0V	-	-	1	μА
IDSS	Zero Gate Voltage Drain Current	$V_{DS} = 64V, T_{C} = 150^{\circ}C$	-	-	500	μΑ
I _{GSS}	Gate to Body Leakage Current	$V_{GS} = \pm 20V, V_{DS} = 0V$	-	-	±100	nA

On Characteristics

$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS} = V_{DS}$, $I_D = 250 \mu A$	2.5	-	4.5	V
R _{DS(on)}	Static Drain to Source On Resistance	V _{GS} = 10V, I _D = 100A	-	3.16	3.9	mΩ
9 _{FS}	Forward Transconductance	$V_{DS} = 10V, I_{D} = 100A$	-	180	-	S

Dynamic Characteristics

C _{iss}	Input Capacitance	V - 40V V - 0V	-	7105	9450	pF
C _{oss}	Output Capacitance	$V_{DS} = 40V, V_{GS} = 0V$ f = 1MHz	-	1110	1475	pF
C _{rss}	Reverse Transfer Capacitance	1 - 1101112	-	30	-	pF
C _{oss(er)}	Energy Related Output Capacitance	V _{DS} = 40V, V _{GS} = 0V	-	1656	-	pF
Q _{g(tot)}	Total Gate Charge at 10V		-	102	133	nC
Q_{gs}	Gate to Source Gate Charge	\/ - 10\/		39.9	-	nC
Q _{gs2}	Gate Charge Threshold to Plateau			20.6	-	nC
Q_{gd}	Gate to Drain "Miller" Charge	(Note 4)	-	22	-	nC
ESR	Equivalent Series Resistance (G-S)	f = 1MHz	-	2.2	-	Ω

Switching Characteristics

t _{d(on)}	Turn-On Delay Time			-	36	82	ns
t _r	Turn-On Rise Time	V _{DD} = 40V, I _D = 100A		-	49	108	ns
t _{d(off)}	Turn-Off Delay Time	V_{GS} = 10V, R_{GEN} = 4.7 Ω		-	71	152	ns
t _f	Turn-Off Fall Time		(Note 4)	-	29	68	ns

Drain-Source Diode Characteristics

I _S	Maximum Continuous Drain to Source Diode Forward Current	-	-	171*	Α
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current	-	-	684	Α
V_{SD}	Drain to Source Diode Forward Voltage V _{GS} = 0V, I _{SD} = 100A	-	-	1.3	V
t _{rr}	Reverse Recovery Time $V_{GS} = 0V, V_{DD} = 40V, I_{SD} = 10$	00A -	70.1	-	ns
Q _{rr}	Reverse Recovery Charge $dI_F/dt = 100A/\mu s$	-	87.9	-	nC

Notes

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature
- 2. L = 3mH, I_{AS} = 19.1A, Starting T_J = 25°C
- 3. I $_{SD}$ \leq 100A, di/dt \leq 200A/ $\mu s,~V_{DD}$ \leq BV $_{DSS},~Starting~T_{J}$ = 25°C
- 4. Essentially Independent of Operating Temperature Typical Characteristics

Typical Performance Characteristics

Figure 1. On-Region Characteristics

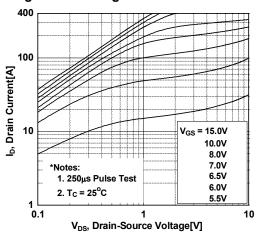


Figure 3. On-Resistance Variation vs.

Drain Current and Gate Voltage

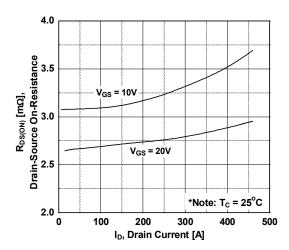


Figure 5. Capacitance Characteristics

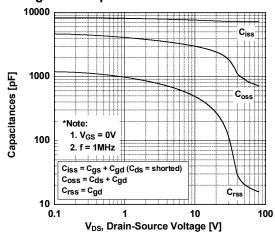


Figure 2. Transfer Characteristics

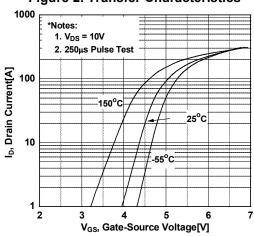


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

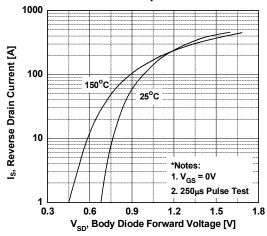
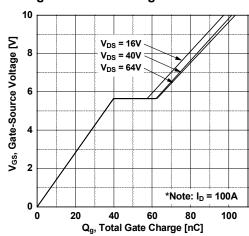


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

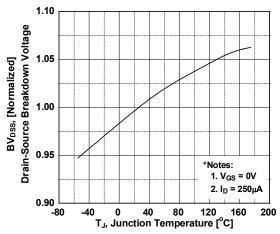


Figure 9. Maximum Safe Operating Area vs. Case Temperature

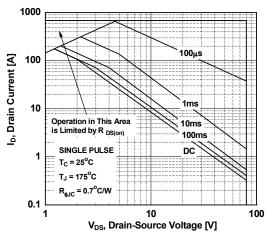


Figure 11. Eoss vs. Drain to Source Voltage

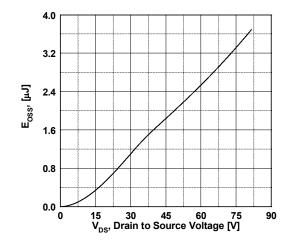


Figure 8. On-Resistance Variation vs. Temperature

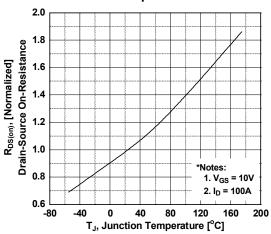


Figure 10. Maximum Drain Current

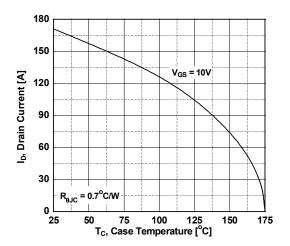
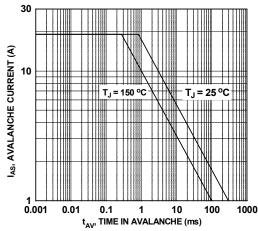
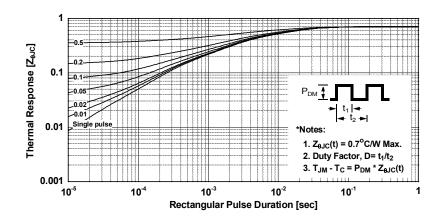


Figure 12. Unclamped Inductive Switching Capability

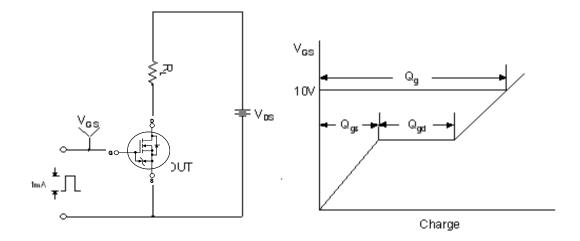


Typical Performance Characteristics (Continued)

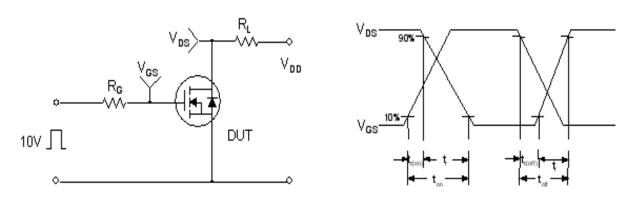




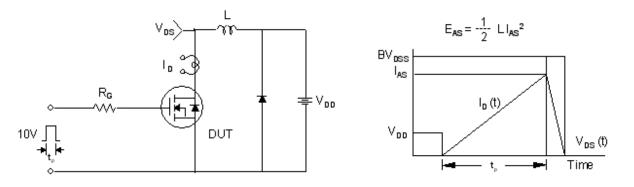
Gate Charge Test Circuit & Waveform



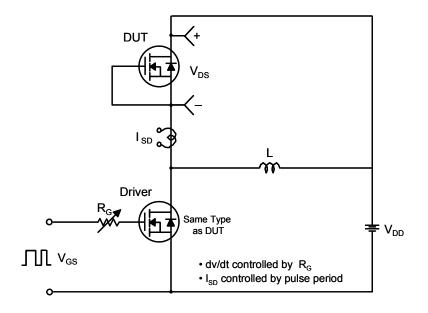
Resistive Switching Test Circuit & Waveforms

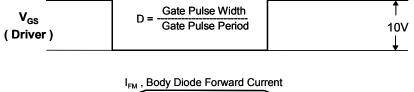


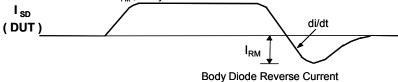
Unclamped Inductive Switching Test Circuit & Waveforms

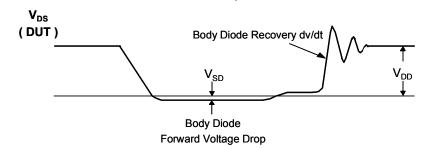


Peak Diode Recovery dv/dt Test Circuit & Waveforms



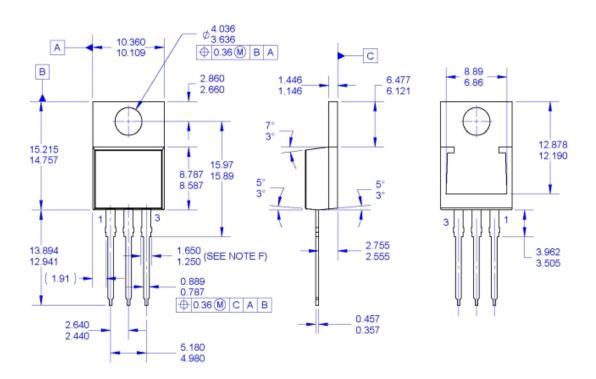


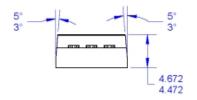




Mechanical Dimensions

TO-220 (F102: Trimmed Leads)





NOTES:

- A. PACKAGE REFERENCE: JEDEC TO220 VARIATION AB B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSION AND TOLERANCE AS PER ASME Y14.5-1994.
- Y14.5-1994.

 D. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS.

 E. THIS PACKAGE IS FSZZ INTERNAL PRODUCTION AND INTENDED FOR DELTA CUSTOMER ONLY.

 F. MAX WIDTH FOR F102 DEVICE = 1.35mm.

 G. DRAWING FILE NAME: TO220T03REV2

Dimensions in Millimeters





TRADEMARKS

The following includes registered and unregistered trademarks and service marks, owned by Fairchild Semiconductor and/or its global subsidiaries, and is not intended to be an exhaustive list of all such trademarks.

2Cool™ AccuPower™ AX-CAP™* BitSiC® Build it Now™ CorePLUS™ CorePOWER™ CROSSVOLT™ CTL™ Current Transfer Logic™ DEUXPEED® Dual Cool™

EcoSPARK® EfficentMax™ ESBC™ Fairchild® Fairchild Semiconductor® FACT Quiet Series™

FACT[®] FAST® FastvCore™ FETBench™ FlashWriter® *

F-PFS™ FRFET® Global Power ResourceSM Green Bridge™ Green FPS™

Green FPS™ e-Series™ Gmax™ GTO™ IntelliMAX™ ISOPI ANAR™ Marking Small Speakers Sound Louder

and Better™ MegaBuck™ MICROCOUPLER™ MicroFET™ MicroPak™

MicroPak2™ MillerDrive™ MotionMax™ Motion-SPM™ mWSaver™ OptoHiT™ OPTOLOGIC® OPTOPLANAR®

®

PowerTrench® PowerXS™

Programmable Active Droop™ **OFET**

QS™ Quiet Series™ RapidConfigure™ тм

Saving our world, 1mW/W/kW at a time™ SignalWise™

SmartMax™ SMART START™

Solutions for Your Success™ SPM®

STEALTH™ SuperFET® SuperSOT™-3 SuperSOT™-6 SuperSOT™-8 SupreMOS® SyncFET™ Sync-Lock™

SYSTEM ®* GENERAL

The Power Franchise®

bwer franchise TinyBoost™ TinyBuck™ TinyCalc™ TinyLogic[®] TIŃYOPTO™ TinyPower™ TinyPWM™ TinyWire™ TranSiC® TriFault Detect™ TRUECURRENT®* SerDes™

UHC® Ultra FRFET™ UniFET™ VCX™ VisualMax™ VoltagePlus™ XSTM

*Trademarks of System General Corporation, used under license by Fairchild Semiconductor

DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION, OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS. THESE SPECIFICATIONS DO NOT EXPAND THE TERMS OF FAIRCHILD'S WORLDWIDE TERMS AND CONDITIONS, SPECIFICALLY THE WARRANTY THEREIN, WHICH COVERS THESE PRODUCTS.

LIFE SUPPORT POLICY
FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION.

- Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury of the user.
- A critical component in any component of a life support, device, or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or

ANTI-COUNTERFEITING POLICY

Fairchild Semiconductor Corporation's Anti-Counterfeiting Policy. Fairchild's Anti-Counterfeiting Policy is also stated on our external website, www.Fairchildsemi.com, under Sales Support.

Counterfeiting of semiconductor parts is a growing problem in the industry. All manufactures of semiconductor products are experiencing counterfeiting of their parts. Customers who inadvertently purchase counterfeit parts experience many problems such as loss of brand reputation, substandard performance, falled application, and increased cost of production and manufacturing delays. Fairchild is taking strong measures to protect ourselves and our customers from the proliferation of counterfeit parts. Fairchild strongly encourages customers to purchase Fairchild parts either directly from Fairchild or from Authorized Fairchild Distributors who are listed by country on our web page cited above. Products customers buy either from Fairchild directly or from Authorized Fairchild Distributors are genuine parts, have full traceability, meet Fairchild's quality standards for handing and storage and provide access to Fairchild's full range of up-to-date technical and product information. Fairchild and our Authorized Distributors will stand behind all warranties and will appropriately address and warranty issues that may arise. Fairchild will not provide any warranty coverage or other assistance for parts bought from Unauthorized Sources. Fairchild is committed to combat this global problem and encourage our customers to do their part in stopping this practice by buying direct or from authorized distributors.

PRODUCT STATUS DEFINITIONS **Definition of Terms**

Datasheet Identification Product Status		Definition
Advance Information Formative / In Design		Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary First Production		Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed Full Production		Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
Obsolete Not In Production		Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.

Rev. 161